



RE231-LF

- Epoxy fibre-glass FR4 1.60 mm
- Double-sided 35 µm Cu
- Not plated through holes (NPTH)
- Hot air leveling (HAL-leadfree)
- Hole spacing 2.54 x 2.54 mm
- 40 x 58 soldering pads 2.00 x 2.00 mm
- Hole diameter 1.02 mm (0.40")
- The component side is totally laminated by copper
- No conducting connection to the component side by etched free holes
- If the copper coating is grounded, the electrical components are optimally shielded against the solder side
- By this HF-, digital and analog circuits can be built up with high reliability
- 2 potential strips
- Max. working temperature 150 °C (302 °F)
- Size 114.30 mm x 165.10 mm (4.5" x 6.5")